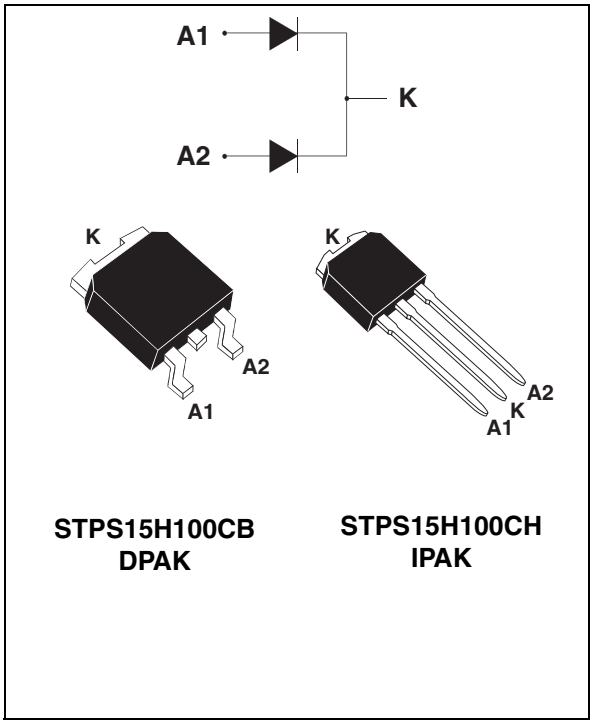
STPS15H100C

High voltage power Schottky rectifier

Main product characteristics

$I_{F(AV)}$	2 x 7.5 A
V_{RRM}	100 V
T_j (max)	175° C
V_F(max)	0.67 V



STPS15H100CB
DPAK

STPS15H100CH
IPAK

Features and Benefits

- Negligible switching losses
- Low leakage current
- Good trade off between leakage current and forward voltage drop
- Low thermal resistance
- Avalanche capability specified

Description

Dual center tab Schottky rectifier suited for switched mode power supply and high frequency DC to DC converters.

Packaged in DPAK and IPAK, this device is intended for use in high frequency inverters.

Table 1. Absolute Ratings (limiting values, per diode)

Symbol	Parameter			Value	Unit
V_{RRM}	Repetitive peak reverse voltage			100	V
$I_{F(RMS)}$	RMS forward current			10	A
$I_{F(AV)}$	Average forward current	T_c = 135° C	Per diode	7.5	A
		δ = 0.5	Per device	15	
I_{FSM}	Surge non repetitive forward current	t_p = 10 ms sinusoidal		75	A
I_{RRM}	Peak repetitive reverse current	t_p = 2 µs square F= 1 kHz		1	A
P_{ARM}	Repetitive peak avalanche power	t_p = 1 µs Tj = 25° C		6600	W
T_{stg}	Storage temperature range			-65 to + 175	°C
T_j	Maximum operating junction temperature (1)			175	°C
dV/dt	Critical rate of rise of reverse voltage			10000	V/µs

1. $\frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

1 Characteristics

Table 2. Thermal resistance

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	Per diode	4	°C/W
		Total	2.4	
$R_{th(c)}$	Coupling		0.7	

When the diodes 1 and 2 are used simultaneously :

ΔT_j(diode 1) = P(diode1) x $R_{th(j-c)}$(Per diode) + P(diode 2) x $R_{th(c)}$

Table 3. Static electrical characteristics (per diode)

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
I_R(1)	Reverse leakage current	T_j = 25° C	$V_R = V_{RRM}$			3	µA
		T_j = 125° C			1.3	4	mA
V_F(1.)	Forward voltage drop	T_j = 25° C	I_F = 7.5 A			0.8	V
		T_j = 125° C	I_F = 7.5 A		0.62	0.67	
		T_j = 25° C	I_F = 12 A			0.85	
		T_j = 125° C	I_F = 12 A		0.68	0.73	
		T_j = 25° C	I_F = 15 A			0.89	
		T_j = 125° C	I_F = 15 A		0.71	0.76	

1. Pulse test: tp = 380 µs, δ < 2%

To evaluate the conduction losses use the following equation:
$P = 0.58 \times I_{F(AV)} + 0.012\ I_F{}^2{}_{(RMS)}$

Figure 1. Conduction losses versus average current

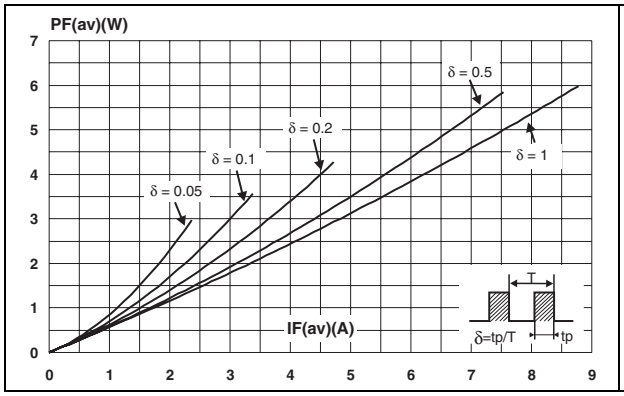


Figure 2. Average forward current versus ambient temperature (δ = 0.5)

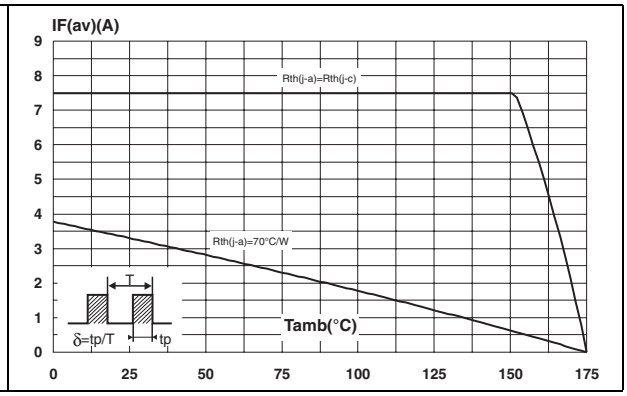


Figure 3. Normalized avalanche power derating versus pulse duration

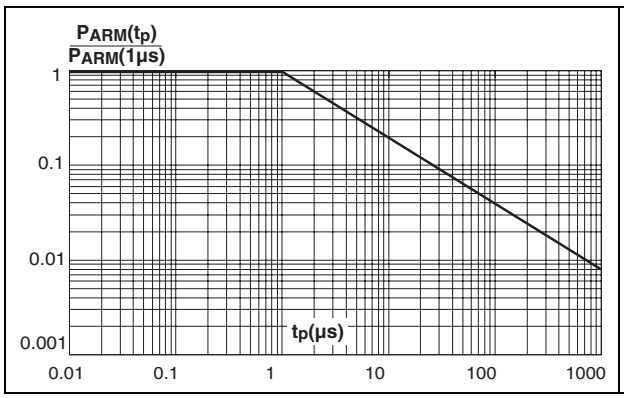


Figure 4. Normalized avalanche power derating versus junction temperature

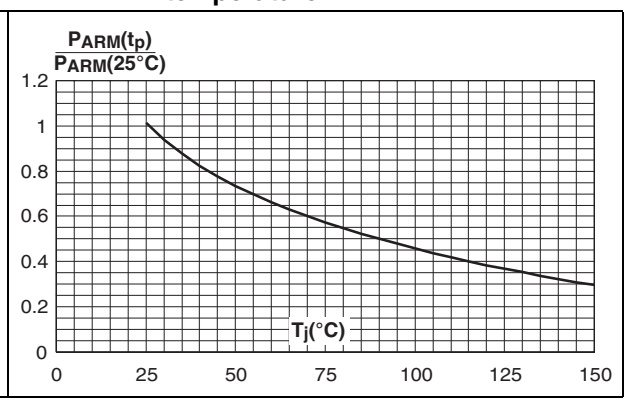


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values)

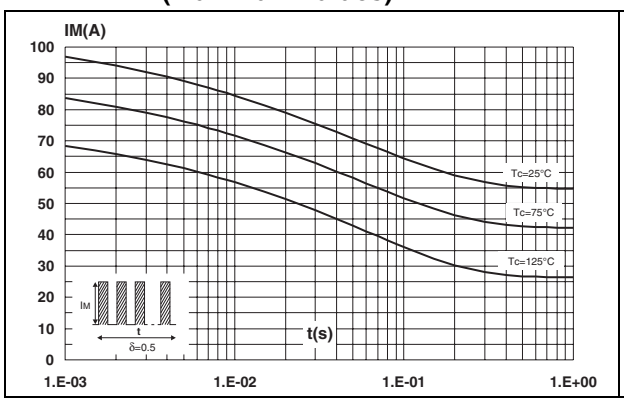


Figure 6. Relative variation of thermal impedance junction to case versus pulse duration

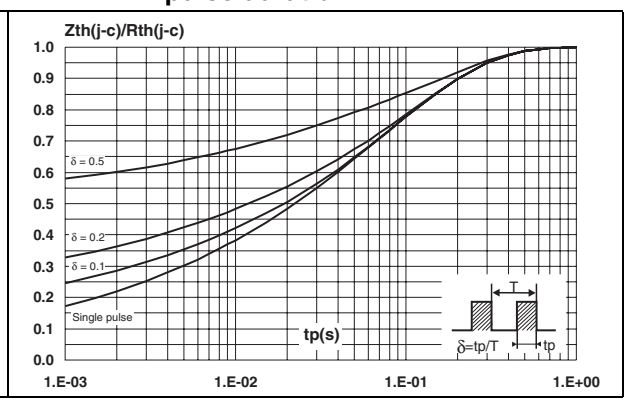


Figure 7. Reverse leakage current versus reverse voltage applied (typical values)

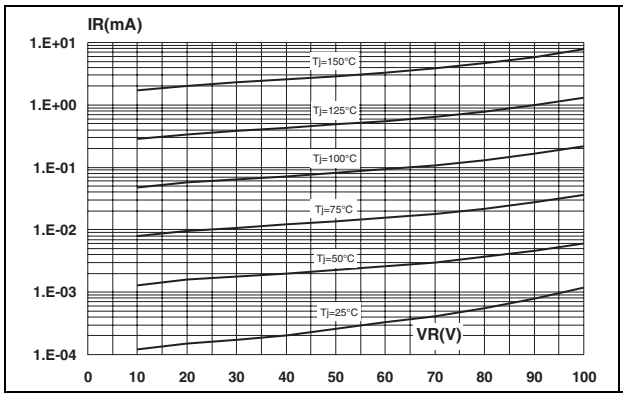


Figure 8. Junction capacitance versus reverse voltage applied (typical values)

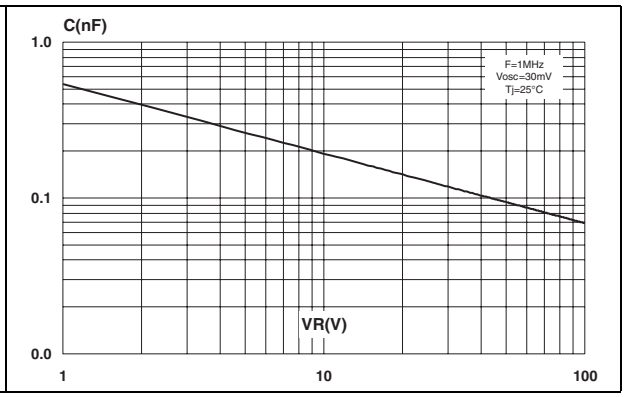


Figure 9. Forward voltage drop versus forward current

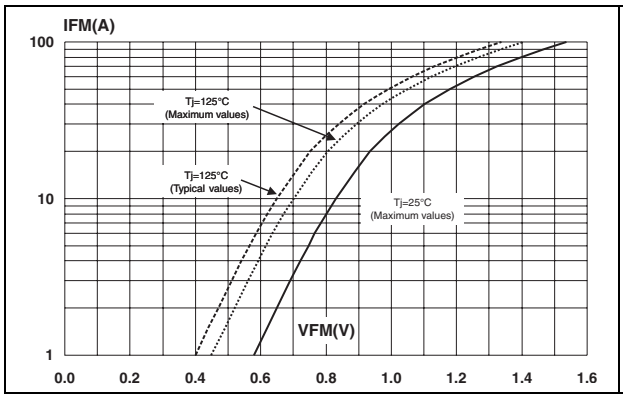
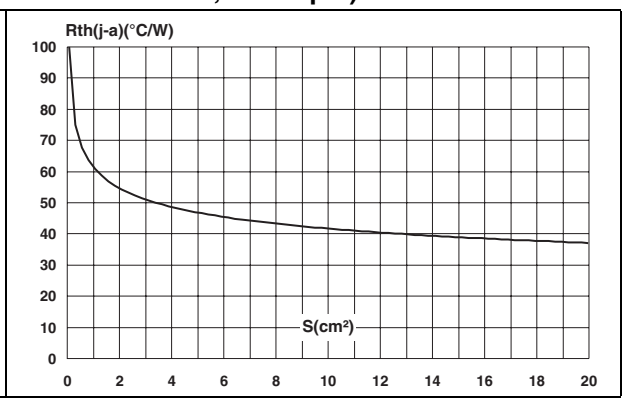


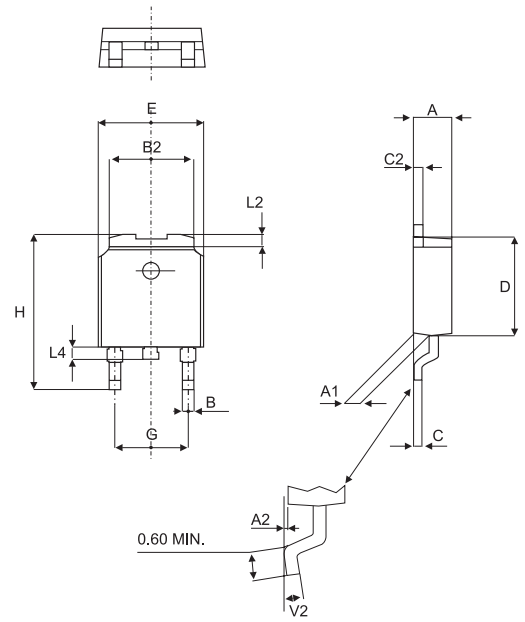
Figure 10. Thermal resistance junction to ambient versus copper surface under tab (epoxy printed board FR4, Cu: 35µm)



2 Package Information

Epoxy meets UL94,V0

Table 4. DPAK Package mechanical data



Ref	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.40	0.086	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
B	0.64	0.90	0.025	0.035
B2	5.20	5.40	0.204	0.212
C	0.45	0.60	0.017	0.023
C2	0.48	0.60	0.018	0.023
D	6.00	6.20	0.236	0.244
E	6.40	6.60	0.251	0.259
G	4.40	4.60	0.173	0.181
H	9.35	10.10	0.368	0.397
L2	0.80 typ.		0.031 typ.	
L4	0.60	1.00	0.023	0.039
V2	0°	8°	0°	8°

Figure 11. DPAK Footprint (dimensions in mm)

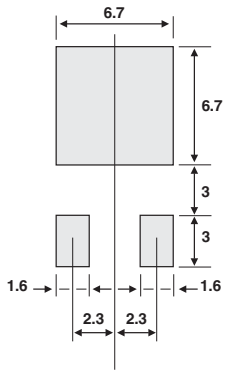
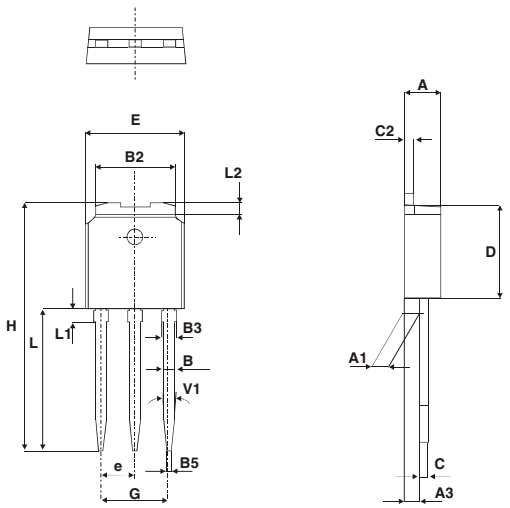


Table 5. IPAK Package mechanical data



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.20		2.40	0.086		0.094
A1	0.90		1.10	0.035		0.043
A3	0.70		1.30	0.027		0.051
B	0.64		0.90	0.025		0.035
B2	5.20		5.40	0.204		0.212
B3			0.95			0.037
B5		0.30			0.035	
C	0.45		0.60	0.017		0.023
C2	0.48		0.60	0.019		0.023
D	6		6.20	0.236		0.244
E	6.40		6.60	0.252		0.260
e		2.28			0.090	
G	4.40		4.60	0.173		0.181
H		16.10			0.634	
L	9		9.40	0.354		0.370
L1	0.8		1.20	0.031		0.047
L2		0.80	1		0.031	0.039
V1		10°			10°	

3 Ordering Information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS15H100CB	S15H100	DPAK	0.30 g	75	Tube
STPS15H100CB-TR	S15H100	DPAK	0.30 g	2500	Tape andreel
STPS15H100CH	S15H100CH	IPAK	0.35 g	75	Tube

4 Revision History

Date	Revision	Changes
Mar-2004	3	Last issue
08-Jun-2006	4	Reformatted to current standard. Added IPAK.

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